AMENDMENTS TO THE CLAIMS

1. - 6. (Cancelled)

7. (Currently Amended) A platemaking method of a lithographic printing plate, comprising developing with friction an exposed lithographic printing plate precursor with a developer, wherein the exposed lithographic printing plate precursor is obtained by an image recording method comprising imagewise exposing a lithographic printing plate precursor with an imaging time per pixel of 1 millisecond or less using a laser light with an emission wavelength selected from 405 nm and 375 nm, wherein the lithographic printing plate precursor comprises a support and an image recording layer, in which the image recording layer contains (A) a polymerization initiator and (B) a polymeric compound and is photosensitive in a wavelength of from 250 nm to 420 nm;

wherein the developer is a non-alkaline developer having a pH value of from 3 to 9 ~~10 or less~~ and comprises an organic solvent that is less than 40% by weight, a nonionic surfactant that has a hydrophile-lipophile balance of 8 or more and is from 0.01 to 10% by weight, and a water-soluble polymeric compound that is from 0.1 to 20% by weight.

8. (Original) The platemaking method according to claim 7, wherein the support has an anodized film with sealed micropores on the surface.

9. (Cancelled)

10. (Currently Amended) The platemaking method according to claim 7, wherein the image recording layer further contains (C) a binder polymer having an ethylenic unsaturated bond in a main chain or a side chain of the binder polymer (C).

11. (Original) The platemaking method according to claim 10, wherein the binder polymer (C) does not have an acid group.

12. (Previously Presented) The platemaking method according to claim 7, wherein the exposure is carried out using an optical system comprising: a DMD or GLV modulation element; and a semiconductor laser with a wavelength of 405 nm or 375 nm.

13. - 14. (Cancelled)

15. (Currently Amended) The platemaking method according to claim 7, wherein the developer further comprises an anionic surfactant.

16. (Cancelled)

17. (New) The platemaking method according to claim 10, wherein a content of an unsaturated double bond in the ethylenic unsaturated bond is from 0.1 to 10.0 mmol relative to 1 gram of the binder polymer.

18. (New) The platemaking method according to claim 7, wherein the support has an undercoat layer containing a compound that contains a polymerizable group and a support-adherent group on the support.

19. (New) The platemaking method according to claim 18, wherein the polymerizable group is selected from the group consisting of a methacryl group and an allyl group.

20. (New) The platemaking method according to claim 18, wherein the support-adherent group is selected from the group consisting of a sulfonic acid group, a phosphoric acid group, and a phosphoric acid ester.

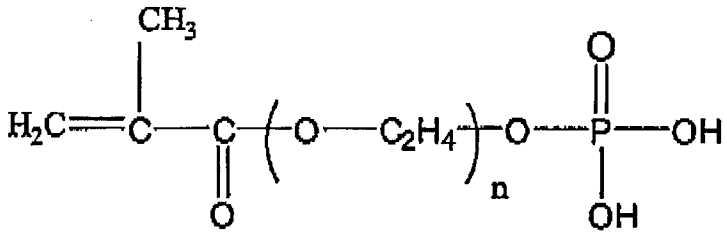
21. (New) The platemaking method according to claim 18, wherein the undercoat layer further contains a hydrophilicity-imparting group.

22. (New) The platemaking method according to claim 21, wherein the hydrophilicity-imparting group is an ethyleneoxy group.

23. (New) The platemaking method according to claim 18, wherein an amount of coating of the undercoat layer is from 1 to 30 mg/m^2.

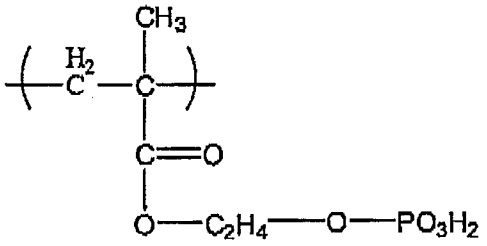
24. (New) The platemaking method according to claim 21, wherein the support-adherent group is selected from the group consisting of a sulfonic acid group, a phosphoric acid group, and a phosphoric acid ester, and the hydrophilicity-imparting group is an ethyleneoxy group.

25. (New) The platemaking method according to claim 24, wherein the undercoat layer contains a compound represented by the following formula:



wherein n represents 4 to 5.

26. (New) The platemaking method according to claim 24, wherein the undercoat layer contains a repeating unit represented by the following formula:



27. (New) The platemaking method according to claim 7, wherein the image recording layer further contains (C) a binder polymer that has an ethylenic unsaturated bond in a main chain or a side chain of the binder polymer (C); and the support has an undercoat layer containing a compound that contains a polymerizable group and a support-adherent group on the support.